NYCU-EE IC LAB – Spring 2024

Lab13 Check List

Self-Verify APR Result

./02_check under 09_SUMBIT to download your Lab13_iclabXXX.tar file back Create a new directory, enter the directory and decompress the tar file. Enter the decompressed directory.

- Make sure your CHIP_iclabXXX.sdc is written correctly: period, waveform parameter, input delay and output delay. Waveform parameter, input delay and output delay should be half of the period.
- Invoke innonus and restore CHIP_iclabXXX.inn
 (Remember to create a new folder in case you overwrite previous design)
- 3. Explore the core size and die size, also verify if the core to IO boundary should be larger than 100.
- 4. Verifying if the IO Filler and the corner pad is added.
- 5. Verify the floorplan and powerplan constraints:
 - a. Power ring: wire group, interleaving, and at least 4 pairs, width 9.
- 6. Post-Route Timing analysis with non-negative slacks, 0 DRVs, core filler added.
- 7. Verifying Geometry and Connectivity after adding core filler cells.
- 8. Latency cycles in post simulation should be the same as gate level simulation. (Clock period: 20ns / Execution cycles: 32000 cycles)